

NON-CORROSIVE LOW TEMPERATURE LIQUID RESIST ADHESIVE

ABSTRACT OF THE DISCLOSURE

Methods of improving the adhesive characteristics of an adhesive resin composition and the use of the adhesive for bonding substrate materials, such as ceramic materials and manufacturing tools, are described. The adhesive composition includes a resist adhesive resin and a solvent having a boiling point in the range of about 30°C to about 80°C. The methods and the adhesive composition find utility in hard disk drive applications, such as in the manufacture of sliders for hard disk drives.